

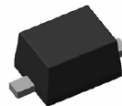
**SURFACE MOUNT FAST SWITCHING DIODE**
**Features**

- Fast Switching Speed
- Low Forward Voltage: Maximum of 0.715V at 1mA
- Fast Reverse Recovery: Maximum of 4ns
- Low Capacitance: Maximum of 1.5pF
- Low Leakage Current: Maximum of 500nA at 80V
- Small Surface Mount Package
- Thermally Efficient Copper Alloy leadframe for High Power Dissipation
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

**Mechanical Data**

- Case: SOD323F
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Copper Alloy leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Weight: 0.003 grams (approximate)

SOD323F



Top View

**Ordering Information** (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
1N4148WSF-7	Standard	JP	7	8	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**


JP = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: A = 2013)  
 M = Month (ex: 9 = September)

## Date Code Key

Year	2013	2014	2015	2016	2017	2018	2019	2020
Code	A	B	C	D	E	F	G	H

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	100	V
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	100	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	71	V
Forward Continuous Current (Note 5)	I <sub>FM</sub>	250	mA
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	@ t = 1.0μs	4.0
		@ t = 1.0ms	1.0
		@ t = 1.0s	0.5

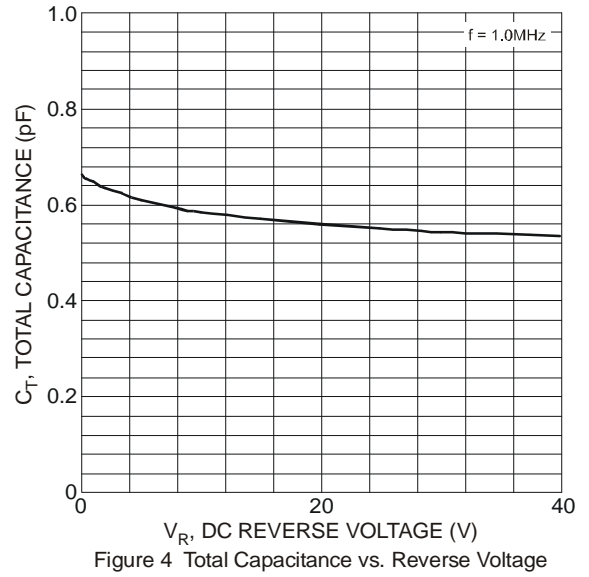
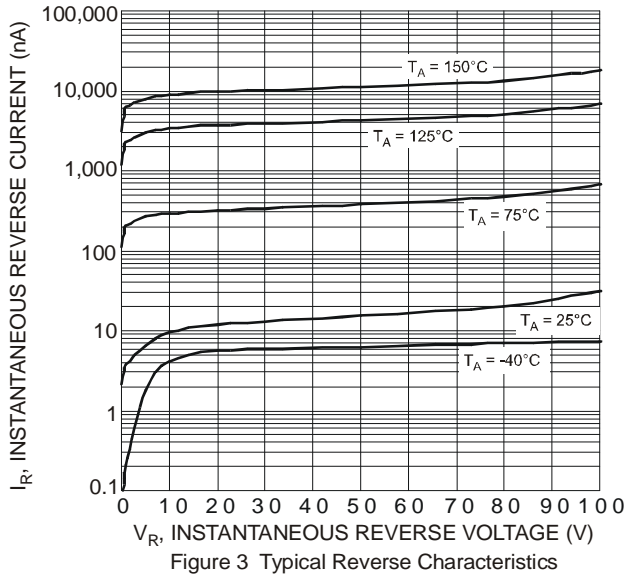
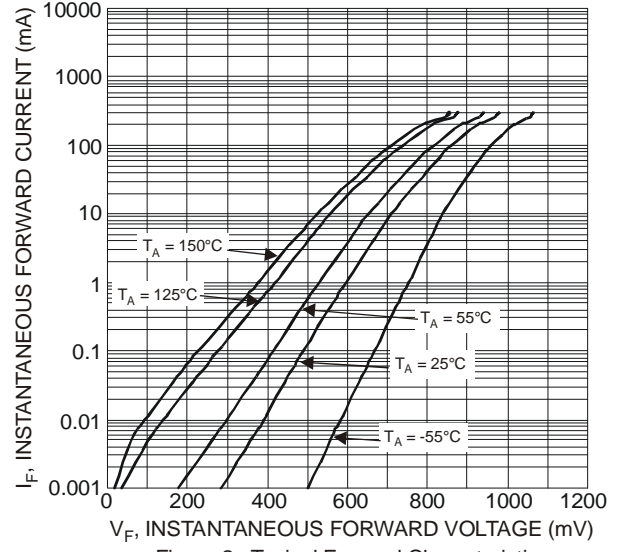
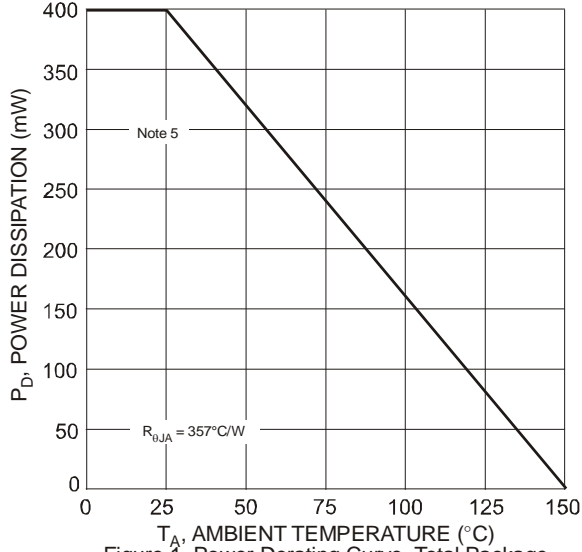
**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	400	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R <sub>θJA</sub>	313	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

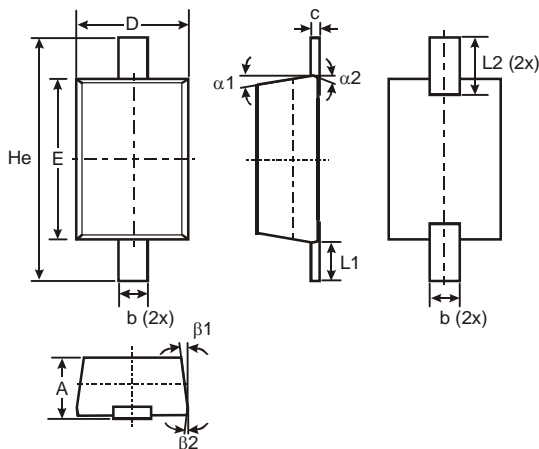
Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	100	—	V	I <sub>R</sub> = 100μA
Forward Voltage	V <sub>F</sub>	—	0.715 0.855 1.0 1.25	V	I <sub>F</sub> = 1.0mA I <sub>F</sub> = 10mA I <sub>F</sub> = 50mA I <sub>F</sub> = 150mA
Leakage Current (Note 6)	I <sub>R</sub>	—	0.5 50 30 30	μA μA μA nA	V <sub>R</sub> = 80V V <sub>R</sub> = 80V, T <sub>J</sub> = +150°C V <sub>R</sub> = 25V, T <sub>J</sub> = +150°C V <sub>R</sub> = 25V
Total Capacitance	C <sub>T</sub>	—	1.5	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	4.0	ns	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>rr</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

- Notes: 5. Device mounted on FR-4 PCB, on minimum recommended, 2oz copper pad layout.  
6. Short duration pulse test used to minimize self-heating effect.



**Package Outline Dimensions**

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

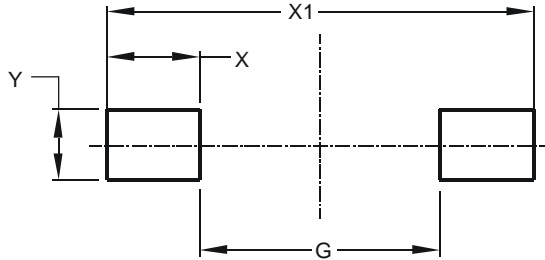


SOD323F			
Dim	Min	Max	Typ
A	0.60	0.75	-
b	0.25	0.35	-
c	0.05	0.26	-
D	1.15	1.35	1.25
E	1.60	1.80	1.70
He	2.30	2.70	2.50
L1	0.30	0.50	0.40
L2	0.41	0.61	0.51
α1	-	-	7°
α2	-	-	3°
β1	-	-	7°
β2	-	-	3°

All Dimensions in mm

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
<b>G</b>	1.280
<b>X</b>	0.710
<b>X1</b>	2.700
<b>Y</b>	0.403

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